

## **PN3646**

# **NPN Switching Transistor**

Sourced from process 22.



1. Emitter 2. Base 3. Collector

## **Absolute Maximum Ratings \*** $T_a$ =25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	15	V
V <sub>CBO</sub>	Collector-Base Voltage	40	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
I <sub>C</sub>	Collector Current - Continued	300	mA
T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

- NOTES:

  1) These ratings are based on a maximum junction temperature of 150 degrees C.

  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

## **Electrical Characteristics** $T_a$ =25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Charact	eristics		•	•	•
BV <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage *	$I_C = 10 \text{mA}, I_B = 0$	15		V
BV <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage	$I_C = 100 \mu A, V_{BE} = 0$	40		V
BV <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 100\mu A, I_E = 0$	40		V
BV <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	5.0		V
I <sub>CES</sub>	Collector Cutoff Current	V <sub>CE</sub> = 20V, V <sub>BE</sub> = 0 V <sub>CE</sub> = 20V, V <sub>BE</sub> = 0, T <sub>a</sub> = 65°C		0.5 3.0	μ <b>Α</b> μ <b>Α</b>
On Characte	eristics *		•	•	
h <sub>FE</sub>	DC Current Gain	$V_{CE} = 0.4V, I_{C} = 30mA$ $V_{CE} = 0.5V, I_{C} = 100mA$ $V_{CE} = 1.0V, I_{C} = 300mA$	30 25 15	120	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	$I_C = 30$ mA, $I_B = 3.0$ mA $I_C = 100$ mA, $I_B = 10$ mA $I_C = 300$ mA, $I_B = 3.0$ mA		0.2 0.28 0.5	V V V
V <sub>BE</sub> (sat)	Base-Emitter Saturation Voltage	$I_C = 30$ mA, $I_B = 3.0$ mA $I_C = 100$ mA, $I_B = 10$ mA $I_C = 300$ mA, $I_B = 3.0$ mA	0.73	0.95 1.2 1.7	V V V
Small Signa	Il Characteristics	•		•	
C <sub>cb</sub>	Collector-Base Capacitance	V <sub>CB</sub> = 5.0V, I <sub>E</sub> = 0, f = 1MHz		5.0	pF
C <sub>eb</sub>	Emitter-Base Capacitance	$V_{CB} = 5.0V, I_{C} = 0, f = 1MHz$		8.0	pF
h <sub>fe</sub>	Small-Signal Current Gain	$I_C = 300 \text{mA}, V_{CE} = 10 \text{V}, f = 100 \text{MHz}$	3.5		

\* Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

# Electrical Characteristics Ta=25°C unless otherwise noted (Continued)

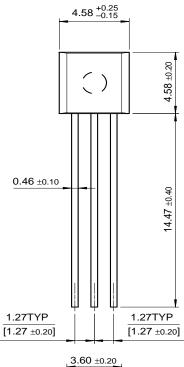
Symbol	Parameter	Test Condition	Min.	Max.	Units
Switching Characteristics					
t <sub>s</sub>	Storage Time	I <sub>C</sub> = 300mA, V <sub>CC</sub> = 10V		20	ns
t <sub>on</sub>	Turn-On Time	$I_{B1} = I_{B2} = 30 \text{mA}$		18	ns
t <sub>off</sub>	Turn-Off Time			28	ns

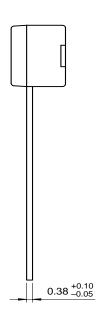
# Thermal Characteristics $\rm T_a=25\,^{\circ}C$ unless otherwise noted

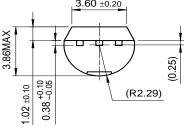
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

# **Package Dimensions**

TO-92







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